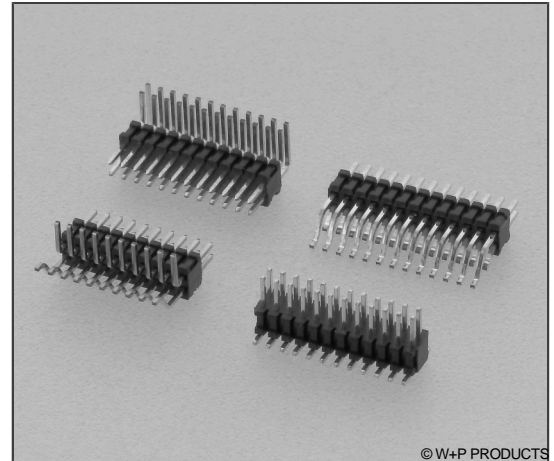


SMT-/ Mixed Technology Stifflisten RM 1,27mm, 2-reihig SMT/Mixed Technology Pin Headers, 1.27mm Pitch, Double Row

Technische Daten / Technical Data

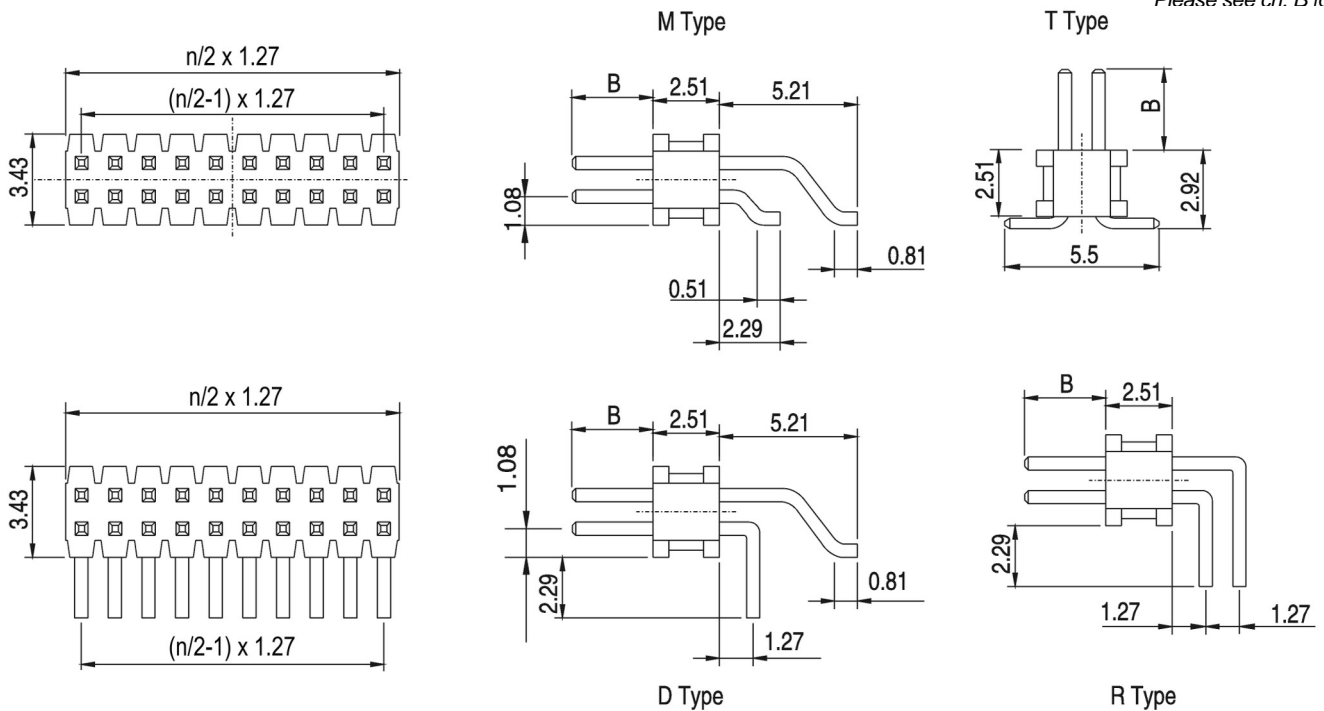
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Vierkantstift 0,40mm, Kupferlegierung
Contact Material	0.40mm square pin, copper alloy
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni
Contact Surface	Acc. to options (see below), over Ni
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 500 MΩ
Insulation Resistance	> 500 MΩ
Spannungsfestigkeit	500 V AC
Test Voltage	500 V AC
Nennspannung	250 V AC
Voltage Rating	250 V AC
Nennstrom	1 A
Current Rating	1 A
Temperaturbereich	-40 °C ... +105 °C
Temperature Range	-40 °C ... +105 °C
Verarbeitung	Reflow- oder Wellen-Lötverfahren
Processing	Reflow- or wave soldering



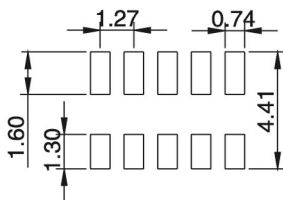
© W+P PRODUCTS

Passende Buchsenleisten:
Compatible Female Headers:
713 7130 etc.

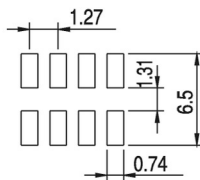
Weitere siehe Kapitel B
Please see ch. B for more



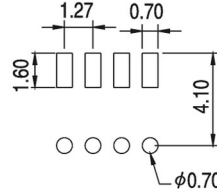
M Type P.C.B Layout



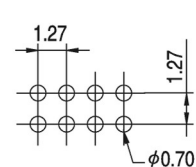
T Type P.C.B Layout



D Type P.C.B Layout



R Type P.C.B Layout

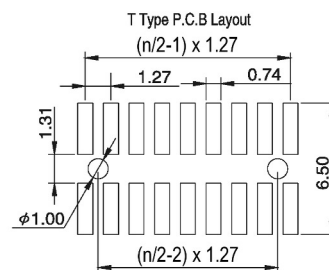
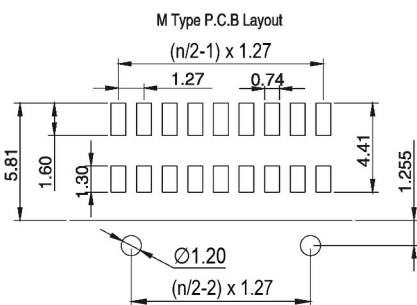
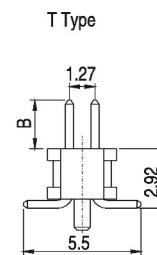
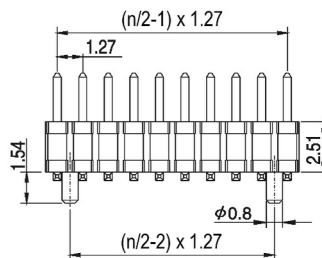
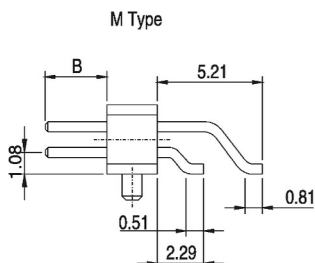
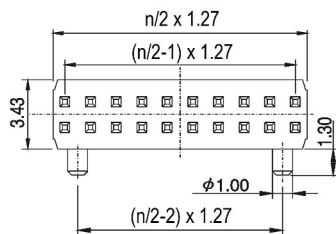
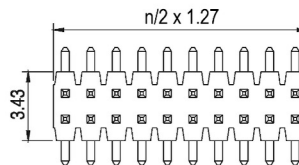
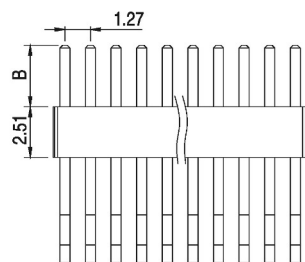


Series	Type*	Dimensions*	Contacts*	Plating*	Loc. Pegs	Packaging*
7076	1	10	004	50	00	PPST
	1 D-Type 2 M-Type 3 T-Type 4 R-Type	10 B=3,05mm 20 B=1,91mm 30 B=1,65mm 40 B=3,81mm	004-070 Zweireihig Double row X- Anfrage Polzahlen More contacts on request	00 Vergoldet Gold plated 50 Verzinkt Tin plated 60 Sel. Au/Sn Duplex plating	00 Ohne Pos.hilfen W/o loc. pegs	ST PPST PPTR (Option)

7076

SMT-/ Mixed Technology Stifflisten RM 1,27mm, 2-reihig

SMT/Mixed Technology Pin Headers, 1.27mm Pitch, Double Row



Series	Type*	Dimensions*	Contacts*	Plating*	Loc. Pegs	Packing*
7076	2	10	004	50	10	PPST
	2 M-Type 3 T-Type	10 B=3,05mm 20 B=1,91mm 30 B=1,65mm 40 B=3,81mm	004-070 Zweireihig Double row X- Anfrage Polzahlen More contacts on request	00 Vergoldet Gold plated 50 Verzinkt Tin plated 60 Sel. Au/Sn Duplex plating	10 Mit Pos.hilfen With loc.pegs	ST In Stangen ohne Pick&Place-Pads In tubes w/o Pick&Place-Pads PPST In Stangen mit P&P-Pads In tubes with P&P-Pads PPTR (Option) Tape & Reel mit P&P-Pads Tape & Reel with P&P-Pads

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** - please replace by your specifications.

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads

PPST In Stangen mit P&P-Pads / In tubes with P&P-Pads

PPTR (Option) Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	217 °C
Duration above T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

